

Claims

[c1] What is claimed is:

1. A wafer holder for semiconductor manufacturing devices, the wafer holder having a wafer-carrying surface and characterized in that the diameter a of the wafer holder wafer-carrying surface is not greater than the diameter b of the wafer holder surface on its side opposite the wafer-carrying surface.
2. The wafer holder set forth in claim 1, wherein the diameter b is larger than the diameter a by $50 \frac{1}{4}m$ or more.
3. The wafer holder set forth in claim 1, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.
4. The wafer holder set forth in claim 2, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.
5. A semiconductor manufacturing device wherein the wafer holder set forth in claim 1 is installed.
6. A semiconductor manufacturing device wherein the wafer holder set forth in claim 2 is installed.
7. A semiconductor manufacturing device wherein the wafer holder set forth in claim 3 is installed.

[c8] 8. A semiconductor manufacturing device wherein the wafer holder set forth in claim 4 is installed.